

Low-profile type with 0.9mm in height



Typical Specifications

Items		Specifications
Rating (max.)/(min.) (Resistive load)		1mA 5V DC / 50 μ A 3V DC
Contact resistance (Initial performance / After lifetime)		200m Ω max. / 300m Ω max.
Operating force		Refer to the dimensions.
Operating life	Without load	10,000 cycles
	With load	10,000 cycles (1mA 5V DC)

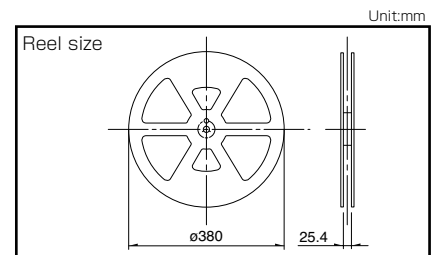
Product Line

Travel (mm)	Operating section directions	Poles	Positions	Changeover timing	Soldering	Location lug	Minimum order unit (pcs.)		Products No.	Drawing No.
							Japan	Export		
1.5	Horizontal	1	3	Not specified	Reflow	With	4,000	16,000	SSAH110100	1
						Without			SSAH120100	2

Packing Specifications

Taping

Number of packages (pcs.)			Tape width (mm)	Export package measurements (mm)
1 reel	1 case /Japan	1 case /export packing		
4,000	8,000	16,000	24	428×413×172

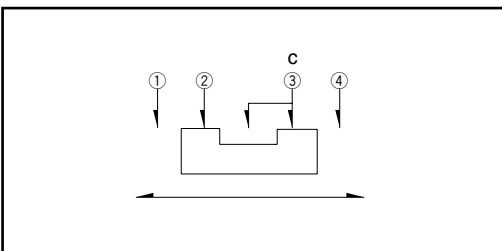


■ Dimensions

Unit:mm

No.	Style	PC board mounting hole and land dimensions (Viewed from the direction A)
1	<p>With boss</p> <p>Terminal No. ①</p> <p>1.2</p> <p>0.4</p> <p>1.2</p> <p>1.5</p> <p>1.5</p> <p>a b c</p> <p>C0.15</p> <p>Travel</p> <p>0.9</p> <p>0.5</p> <p>ø0.8</p> <p>7</p> <p>9.5</p> <p>0.5</p> <p>0.44</p> <p>0.7</p> <p>1.5</p> <p>3</p> <p>0.1</p> <p>PC board mounting face</p> <p>a → b } 0.9N b → a } 1.2N c → b } 0.9N b → c } 1.2N</p>	<p>2-ø0.9 hole</p> <p>9.1</p> <p>7</p> <p>1.1</p> <p>1.9</p> <p>1.6</p> <p>1.1</p> <p>(1.5)</p> <p>Note the arrangement of circuit patterns at \square range</p>
2	<p>Terminal No. ①</p> <p>1.2</p> <p>0.4</p> <p>1.2</p> <p>1.5</p> <p>1.5</p> <p>a b c</p> <p>C0.15</p> <p>Travel</p> <p>0.9</p> <p>0.5</p> <p>ø0.8</p> <p>7</p> <p>9.5</p> <p>0.5</p> <p>0.44</p> <p>0.7</p> <p>1.5</p> <p>3</p> <p>0.1</p> <p>PC board mounting face</p> <p>a → b } 0.9N b → a } 1.2N c → b } 0.9N b → c } 1.2N</p>	<p>2-ø0.9 hole</p> <p>9.1</p> <p>7</p> <p>1.1</p> <p>1.9</p> <p>1.6</p> <p>1.1</p> <p>(1.5)</p> <p>Note the arrangement of circuit patterns at \square range</p>













■ Circuit Diagram (Viewed from Direction A)



Detector
Slide
Push
Rotary
Power
Dual-In-line
Package Type
Small size
General Use Type
Big size
General Use Type

Slide Switches

List of Varieties

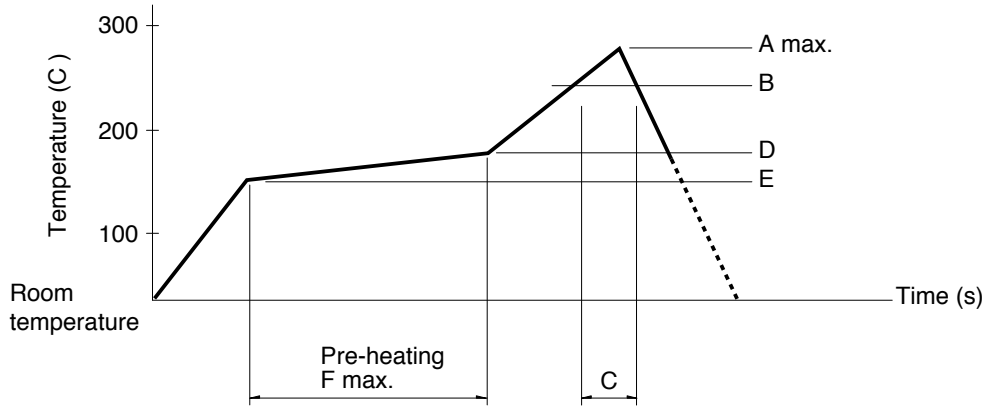
Series		SSAJ	SSAH	SSSS8	SSAL	SSAG	SSSS7
Photo							
Actuator direction	Horizontal	●	●	●	●	●	●
	Vertical	—	—	●	—	—	—
Poles-positions	1-2	●	—	●	●	—	●
	1-3	—	●	●	—	●	●
	1-4	—	—	—	—	—	—
	2-2	—	—	●	—	—	—
	2-3	—	—	●	—	—	—
	2-4	—	—	—	—	—	—
	4-2	—	—	—	—	—	—
Travel (mm)		1.4	1.5	1.5, 2	2	1.5	2
Operating temperature range		-10°C to +60°C	-30°C to +60°C	-40°C to +85°C	-10°C to +60°C		-40°C to +85°C
Automotive use		—	—	—	—	—	—
Life cycle							
Rating (max.) (Resistive load)		10mA 5V DC	1mA 5V DC	0.3A 5V DC	10mA 5V DC		0.3A 4V DC
Rating (min.) (Resistive load)		50μA 3V DC					
Durability	Operating life without load	10,000 cycles 500mΩ max.	10,000 cycles 300mΩ max.	10,000 cycles 100mΩ max.	100,000 cycles 10Ω max.	30,000 cycles (Lock side) 100,000 cycles (Recoil side) 500mΩ max.	10,000 cycles 100mΩ max.
	Operating life with load Load: as rating			10,000 cycles 130mΩ max.			10,000 cycles 130mΩ max.
Electrical performance	Initial contact resistance	300mΩ max.	200mΩ max.	70mΩ max.	10Ω max.	200mΩ max.	70mΩ max.
	Insulation resistance	100MΩ min. 100V DC					
	Voltage proof	100V AC for 1minute					
Mechanical performance	Terminal strength	3N for 1minute					
	Actuator strength	10N					
Environmental performance	Cold	-40°C 96h		-40°C 500h	-40°C 96h		-20°C 500h
	Dry heat	85°C 96h		85°C 500h	85°C 96h		85°C 500h
	Damp heat	40°C, 90 to 95%RH 96h	60°C, 90 to 95%RH 240h	60°C, 90 to 95%RH 500h	40°C, 90 to 95%RH 96h		60°C, 90 to 95%RH 500h
Page		70	72	74	77	79	82

Slide Switches Soldering Conditions	106
Slide Switches Cautions	107

Note
 ● Indicates applicability to all products in the series.

Example of Reflow Soldering Condition

1. Heating method: Double heating method with infrared heater.
2. Temperature measurement: Thermocouple ϕ 0.1 to 0.2 CA (K) or CC (T) at soldering portion (copper foil surface).
A heat resisting tape should be used for fixed measurement.
3. Temperature profile



Series (Reflow type)		A (°C) 3s max.	B (°C)	C (s)	D (°C)	E (°C)	F (s)
SSSS2	Vertical 1-pole, 3-position	260	230	40	180	150	120
	Horizontal 1-pole, 2-position 1-pole, 3-position 2-pole, 3-position						
	Vertical 1-pole, 2-position	250					
SSSS7		260					
SSAH, SSAG, SSAJ, SSAL, SSSS8		260					

Notes

1. The condition mentioned above is the temperature on the mounting surface of a PC board. There are cases where the PC board's temperature greatly differs from that of the switch, depending on the PC board's material, size, thickness, etc. The above-stated conditions shall also apply to switch surface temperatures.
2. Soldering conditions differ depending on reflow soldering machines. Prior verification of soldering condition is highly recommended.

Reference for Hand Soldering

Series	Soldering temperature	Soldering time
SSSF, SSSU	350±10°C	3+1/0s
SSSS2	350±10°C	4s max.
SSSS9	350±10°C	3s max.
SSAH, SSAG, SSAJ, SSAL	350±5°C	3s max.
SSSS8	330±5°C	3s max.
SSSS7	320±5°C	3s max.
SSAC	300±10°C	2s max.

Reference for Dip Soldering

(For PC board terminal types)

Series	Items		Dip soldering	
	Preheating temperature	Preheating time	Soldering temperature	Duration of immersion
SSSS2	100°C max.	60s max.	260±5°C	3±1s
SSSS9	120°C max.	60s max.	260±5°C	5+0/-1s (2 times)
SSSF, SSSU	100°C max.	60s max.	260±5°C	10±1s/5±1s
SSAC	100°C max.	60s max.	260±5°C	5±1s